# ESDR0544M

# Transient Voltage Suppressors

# Low Capacitance ESD Protection for High Speed Data

The ESDR0544M transient voltage suppressor is designed to protect high speed data lines from ESD. Ultra-low capacitance and low ESD clamping voltage make this device an ideal solution for protecting voltage sensitive high speed data lines. The flow-through style package allows for easy PCB layout and matched trace lengths necessary to maintain consistent impedance between high speed differential lines such as HDMI.

## Features

- Low Capacitance (0.9 pF Max Between I/O Lines and Ground)
- ESD Rating of Class 3B (Exceeding 8 kV) per Human Body model and Class C (Exceeding 400 V) per Machine Model
- Protection for the Following IEC Standards: IEC 61000-4-2 (8 kV Contact)
- UL Flammability Rating of 94 V-0
- This is a Pb–Free Device

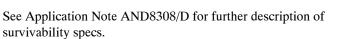
### **Typical Applications**

- HDMI
- DVI
- Display Port
- MDDI
- eSATA

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Operating Junction Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C
Lead Solder Temperature – Maximum (10 Seconds)	ΤL	260	°C
IEC 61000-4-2 Contact (ESD)	ESD	8.0	kV

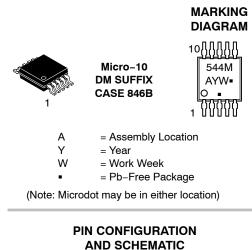
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

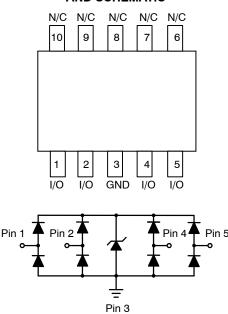




## **ON Semiconductor®**

http://onsemi.com





#### **ORDERING INFORMATION**

Device	Package	Shipping
ESDR0544MDMR4G	Micro-10 (Pb-Free)	1000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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Publication Order Number: ESDR0544M/D

## ESDR0544M

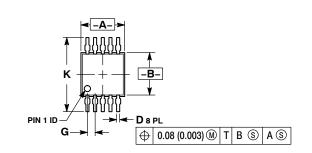
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse Working Voltage	V <sub>RWM</sub>	(Note 1)			5.0	V
Breakdown Voltage	V <sub>BR</sub>	I <sub>T</sub> = 1 mA, (Note 2)	6.0			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> = 5 V			1.0	μA
Junction Capacitance	CJ	$V_{R}$ = 0 V, f = 1 MHz between I/O Pins and GND		0.7	0.9	pF
Junction Capacitance	CJ	$V_R = 0 V$ , f = 1 MHz between I/O Pins		0.3	0.7	pF

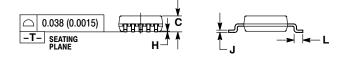
TVS devices are normally selected according to the working peak reverse voltage (V<sub>RWM</sub>), which should be equal or greater than the DC or continuous peak operating voltage level.
 V<sub>BR</sub> is measured at pulse test current I<sub>T</sub>.

#### ESDR0544M

#### PACKAGE DIMENSIONS

Micro-10 CASE 846B-03 ISSUE D



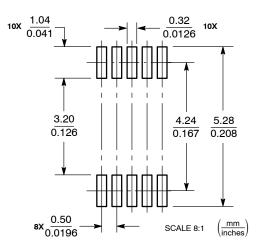


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: MILLIMETER.
- CONTROLLING DIMENSION: MILLIMETER.
  DIMENSION 'A" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) DED SIDE
- PER SIDE.
  DIMENSION "B" DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- SHALL NOT EXCEED 0.25 (0.010) PER SIDE
  846B–01 OBSOLETE. NEW STANDARD
  846B–02

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.95	1.10	0.037	0.043
D	0.20	0.30	0.008	0.012
G	0.50 BSC		0.020 BSC	
Н	0.05	0.15	0.002	0.006
J	0.10	0.21	0.004	0.008
Κ	4.75	5.05	0.187	0.199
L	0.40	0.70	0.016	0.028

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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